

1 (twice amended). A system comprising:

a processor; and

a memory device operatively coupled to the processor, the memory device comprising a plurality of vertically stacked ball grid arrays, each ball grid array having a memory chip, and wherein the vertically stacked ball grid arrays comprise:

a plurality of packages, each of the plurality of packages comprising a plurality of non-metal mateable alignment features, and wherein each of the plurality of packages is physically coupled to another of the plurality of packages; and

a plurality of memory chips, each of the plurality of memory chips physically coupled to a respective one of the plurality of packages.

15 (twice amended). A memory board comprising:

a substrate; and

a memory device operatively coupled to the substrate, the memory device comprising a plurality of vertically stacked ball grid arrays, each ball grid array having a memory chip, and wherein the vertically stacked ball grid arrays comprise:

a plurality of packages, each of the plurality of packages comprising a plurality of non-metal mateable alignment features, and wherein each of the plurality of packages is physically coupled to another of the plurality of packages; and

→ a plurality of memory chips, each of the plurality of memory chips coupled to a respective one of the plurality of packages.

33 (twice amended). A stacked ball grid array comprising:

a plurality of packages, each of the plurality of packages comprising a plurality of non-metal mateable alignment features, and each of the plurality of packages coupled to another of the plurality of packages; and

a plurality of memory chips, each of the plurality of memory chips coupled to a respective one of the plurality of packages.

47 (twice amended). A device comprising:

a chip; and

a package operatively coupled to the chip, the package comprising:

a first side;

a second side;

a plurality of first non-metal mateable alignment features on the first side of the package; and

a plurality of second non-metal mateable alignment features on the second side of the package.

54 (twice amended). A package comprising:

a first side;

a second side;

a plurality of first non-metal mateable alignment features on the first side of the package;
and

a plurality of second non-metal mateable alignment features on the second side of the package.